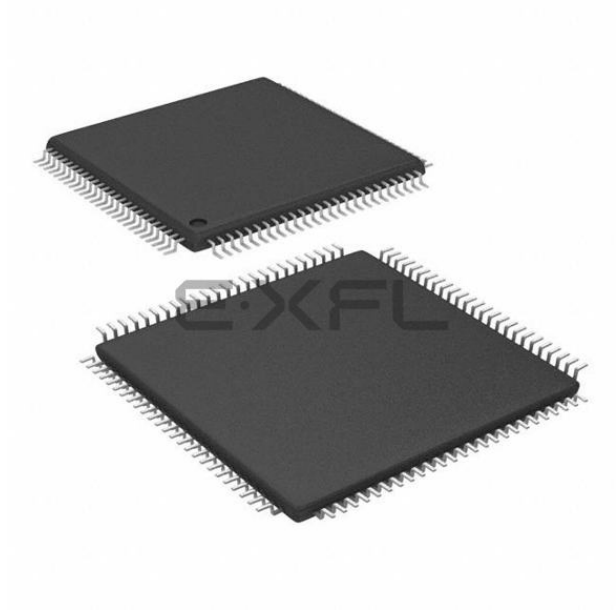
Microchip Technology - PIC32MX450F256LT-120/PF Datasheet



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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	120MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	81
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 28x10b
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx450f256lt-120-pf

TABLE 3: PIN NAMES FOR 64-PIN DEVICES

64-PIN QFN(1,2) AND TQFP(1,2) (TOP VIEW)

PIC32MX430F064H
PIC32MX450F128H
PIC32MX450F256H
PIC32MX470F512H

64 1

QFN(3)

64 1

TQFP

Pin #	Full Pin Name	Pin #	Full Pin Name
1	AN22/RPE5/PMD5/RE5	33	USBID/RF3
2	AN23/PMD6/RE6	34	VBUS
3	AN27/PMD7/RE7	35	VUSB3V3
4	AN16/C1IND/RPG6/SCK2/PMA5/RG6	36	D-
5	AN17/C1INC/RPG7/PMA4/RG7	37	D+
6	AN18/C2IND/RPG8/PMA3/RG8	38	VDD
7	$\overline{\text{MCLR}}$	39	OSC1/CLKI/RC12
8	AN19/C2INC/RPG9/PMA2/RG9	40	OSC2/CLKO/RC15
9	VSS	41	VSS
10	VDD	42	RPD8/RTCC/RD8
11	AN5/C1INA/RPB5/VBUSON/RB5	43	RPD9/SDA1/RD9
12	AN4/C1INB/RB4	44	RPD10/SCL1/PMCS2/RD10
13	PGED3/AN3/C2INA/RPB3/RB3	45	RPD11/PMCS1/RD11
14	PGEC3/AN2/C2INB/RPB2/CTED13/RB2	46	RPD0/INT0/RD0
15	PGEC1/VREF-/CVREF-/AN1/RPB1/CTED12/RB1	47	SOSCI/RPC13/RC13
16	PGED1/VREF+/CVREF+/AN0/RPB0/PMA6/RB0	48	SOSCO/RPC14/T1CK/RC14
17	PGEC2/AN6/RPB6/RB6	49	AN24/RPD1/RD1
18	PGED2/AN7/RPB7/CTED3//RB7	50	AN25/RPD2/SCK1/RD2
19	AVDD	51	AN26/RPD3/RD3
20	AVSS	52	RPD4/PMWR/RD4
21	AN8/RPB8/CTED10//RB8	53	RPD5/PMRD/RD5
22	AN9/RPB9/CTED4/PMA7/RB9	54	RD6
23	TMS/CVREFOUT/AN10/RPB10/CTED11//PMA13/RB10	55	RD7
24	TDO/AN11/PMA12/RB11	56	VCAP
25	VSS	57	VDD
26	VDD	58	RPF0/RF0
27	TCK/AN12/PMA11/RB12	59	RPF1/RF1
28	TDI/AN13/PMA10/RB13	60	PMD0/RE0
29	AN14/RPB14/CTED5/PMA1/RB14	61	PMD1/RE1
30	AN15/RPB15/OCFB/CTED6/PMA0/RB15	62	AN20/PMD2/RE2
31	RPF4/SDA2/PMA9/RF4	63	RPE3/CTPLS/PMD3/RE3
32	RPF5/SCL2/PMA8/RF5	64	AN21/PMD4/RE4

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 12.3 "Peripheral Pin Select"** for restrictions.

2: Every I/O port pin (RBx-RGx) can be used as a change notification pin (CNBx-CNGx). See **Section 12.0 "I/O Ports"** for more information.

3: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	64-pin QFN/ TQFP	100-pin TQFP	124-pin VTLA			
IC1	PPS	PPS	PPS	I	ST	Capture Input 1-5
IC2	PPS	PPS	PPS	I	ST	
IC3	PPS	PPS	PPS	I	ST	
IC4	PPS	PPS	PPS	I	ST	
IC5	PPS	PPS	PPS	I	ST	
OC1	PPS	PPS	PPS	O	ST	Output Compare Output 1
OC2	PPS	PPS	PPS	O	ST	Output Compare Output 2
OC3	PPS	PPS	PPS	O	ST	Output Compare Output 3
OC4	PPS	PPS	PPS	O	ST	Output Compare Output 4
OC5	PPS	PPS	PPS	O	ST	Output Compare Output 5
OCFA	PPS	PPS	PPS	I	ST	Output Compare Fault A Input
OCFB	30	44	A29	I	ST	Output Compare Fault B Input
INT0	35(1), 46(2)	55(1), 72(2)	B30(1), B39(2)	I	ST	External Interrupt 0
INT1	PPS	PPS	PPS	I	ST	External Interrupt 1
INT2	PPS	PPS	PPS	I	ST	External Interrupt 2
INT3	PPS	PPS	PPS	I	ST	External Interrupt 3
INT4	PPS	PPS	PPS	I	ST	External Interrupt 4
RA0	—	17	B9	I/O	ST	PORTA is a bidirectional I/O port
RA1	—	38	A26	I/O	ST	
RA2	—	58	A39	I/O	ST	
RA3	—	59	B32	I/O	ST	
RA4	—	60	A40	I/O	ST	
RA5	—	61	B33	I/O	ST	
RA6	—	91	B51	I/O	ST	
RA7	—	92	A62	I/O	ST	
RA9	—	28	A21	I/O	ST	
RA10	—	29	B17	I/O	ST	
RA14	—	66	B36	I/O	ST	
RA15	—	67	A44	I/O	ST	

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
TTL = TTL input buffer

Note 1: This pin is only available on devices without a USB module.
2: This pin is only available on devices with a USB module.
3: This pin is not available on 64-pin devices.

2.5 ICSP Pins

The PGECx and PGEDx pins are used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes and capacitors on the PGECx and PGEDx pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (V_{IH}) and input low (V_{IL}) requirements.

Ensure that the "Communication Channel Select" (i.e., PGECx/PGEDx pins) programmed into the device matches the physical connections for the ICSP to MPLAB® ICD 3 or MPLAB REAL ICE™.

For more information on ICD 3 and REAL ICE connection requirements, refer to the following documents that are available on the Microchip web site.

- *"Using MPLAB® ICD 3"* (poster) DS50001765
- *"MPLAB® ICD 3 Design Advisory"* DS50001764
- *"MPLAB® REAL ICE™ In-Circuit Debugger User's Guide"* DS50001616
- *"Using MPLAB® REAL ICE™ Emulator"* (poster) DS50001749

2.6 JTAG

The TMS, TDO, TDI and TCK pins are used for testing and debugging according to the Joint Test Action Group (JTAG) standard. It is recommended to keep the trace length between the JTAG connector and the JTAG pins on the device as short as possible. If the JTAG connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

Pull-up resistors, series diodes and capacitors on the TMS, TDO, TDI and TCK pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits and pin input voltage high (V_{IH}) and input low (V_{IL}) requirements.

2.7 Trace

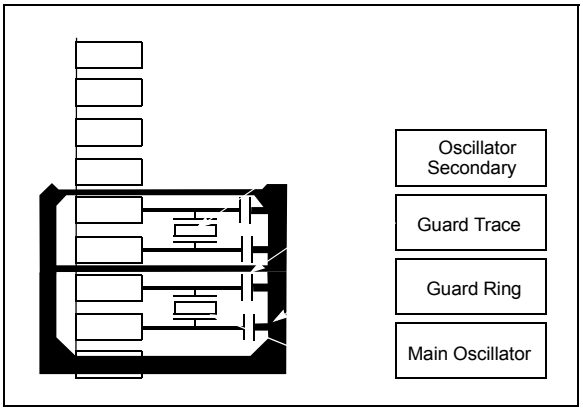
The trace pins can be connected to a hardware trace-enabled programmer to provide a compressed real-time instruction trace. When used for trace, the TRD3, TRD2, TRD1, TRD0 and TRCLK pins should be dedicated for this use. The trace hardware requires a 22 Ohm series resistor between the trace pins and the trace connector.

2.8 External Oscillator Pins

Many MCUs have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator (refer to **Section 8.0 "Oscillator Configuration"** for details).

The oscillator circuit should be placed on the same side of the board as the device. Also, place the oscillator circuit close to the respective oscillator pins, not exceeding one-half inch (12 mm) distance between them. The load capacitors should be placed next to the oscillator itself, on the same side of the board. Use a grounded copper pour around the oscillator circuit to isolate them from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed. A suggested layout is illustrated in Figure 2-3.

FIGURE 2-3: SUGGESTED OSCILLATOR CIRCUIT PLACEMENT



5.1 Control Registers

TABLE 5-1: FLASH CONTROLLER REGISTER MAP

Virtual Address (BF80_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
F400	NVMCON(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	WR	WREN	WRERR	LVDERR	LVDSTAT	—	—	—	—	—	—	—	NVMOP<3:0>				0000
F410	NVMKEY	31:16	NVMKEY<31:0>																0000
		15:0																	0000
F420	NVMADDR(1)	31:16	NVMADDR<31:0>																0000
		15:0																	0000
F430	NVMDATA	31:16	NVMDATA<31:0>																0000
		15:0																	0000
F440	NVMSRC ADDR	31:16	NVMSRCADDR<31:0>																0000
		15:0																	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.2 "CLR, SET, and INV Registers"** for more information.

REGISTER 6-2: RSWRST: SOFTWARE RESET REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	U-0	U-0	U-0	U-0	U-0	U-0	U-0	W-0, HC
	—	—	—	—	—	—	—	SWRST(1)

Legend:	HC = Cleared by hardware		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-1 **Unimplemented:** Read as '0'

bit 0 **SWRST:** Software Reset Trigger bit(1)

1 = Enable software Reset event

0 = No effect

Note 1: The system unlock sequence must be performed before the SWRST bit can be written. Refer to **Section 6. "Oscillator"** (DS60001112) in the *"PIC32 Family Reference Manual"* for details.

REGISTER 8-3: REFOCON: REFERENCE OSCILLATOR CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	RODIV<14:8>(1,3)						
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	RODIV<7:0>(3)							
15:8	R/W-0	U-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0, HC	R-0, HS, HC
	ON	—	SIDL	OE	RSLP(2)	—	DIVSWEN	ACTIVE
7:0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	—	—	ROSEL<3:0>(1)			

Legend:	HC = Hardware Clearable	HS = Hardware Settable	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31 **Unimplemented:** Read as '0'

bit 30-16 **RODIV<14:0>:** Reference Clock Divider bits(1,3)
This value selects the Reference Clock Divider bits. See Figure 8-1 for more information.

bit 15 **ON:** Output Enable bit
1 = Reference Oscillator Module is enabled
0 = Reference Oscillator Module is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **SIDL:** Peripheral Stop in Idle Mode bit
1 = Discontinue module operation when device enters Idle mode
0 = Continue module operation in Idle mode

bit 12 **OE:** Reference Clock Output Enable bit
1 = Reference clock is driven out on REFCLKO pin
0 = Reference clock is not driven out on REFCLKO pin

bit 11 **RSLP:** Reference Oscillator Module Run in Sleep bit(2)
1 = Reference Oscillator Module output continues to run in Sleep
0 = Reference Oscillator Module output is disabled in Sleep

bit 10 **Unimplemented:** Read as '0'

bit 9 **DIVSWEN:** Divider Switch Enable bit
1 = Divider switch is in progress
0 = Divider switch is complete

bit 8 **ACTIVE:** Reference Clock Request Status bit
1 = Reference clock request is active
0 = Reference clock request is not active

bit 7-4 **Unimplemented:** Read as '0'

Note 1: The ROSEL and RODIV bits should not be written while the ACTIVE bit is '1', as undefined behavior may result.

2: This bit is ignored when the ROSEL<3:0> bits = 0000 or 0001.

3: While the ON bit is set to '1', writes to these bits do not take effect until the DIVSWEN bit is also set to '1'.

REGISTER 10-4: DCRCCON: DMA CRC CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0
	—	—	BYTO<1:0>		WBO(1)	—	—	BITO(1)
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	—	PLEN<4:0>				
7:0	R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0
	CRCEN	CRCAPP(1)	CRCTYP	—	—	CRCCH<2:0>		

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-30 **Unimplemented:** Read as '0'

bit 29-28 **BYTO<1:0>:** CRC Byte Order Selection bits
- 11 = Endian byte swap on half-word boundaries (i.e., source half-word order with reverse source byte order per half-word)
- 10 = Swap half-words on word boundaries (i.e., reverse source half-word order with source byte order per half-word)
- 01 = Endian byte swap on word boundaries (i.e., reverse source byte order)
- 00 = No swapping (i.e., source byte order)

bit 27 **WBO:** CRC Write Byte Order Selection bit(1)
- 1 = Source data is written to the destination re-ordered as defined by BYTO<1:0>
- 0 = Source data is written to the destination unaltered

bit 26-25 **Unimplemented:** Read as '0'

bit 24 **BITO:** CRC Bit Order Selection bit(1)

When CRCTYP (DCRCCON<15>) = 1 (CRC module is in IP Header mode):
- 1 = The IP header checksum is calculated Least Significant bit (LSb) first (i.e., reflected)
- 0 = The IP header checksum is calculated Most Significant bit (MSb) first (i.e., not reflected)

When CRCTYP (DCRCCON<15>) = 0 (CRC module is in LFSR mode):
- 1 = The LFSR CRC is calculated Least Significant bit first (i.e., reflected)
- 0 = The LFSR CRC is calculated Most Significant bit first (i.e., not reflected)

bit 23-13 **Unimplemented:** Read as '0'

bit 12-8 **PLEN<4:0>:** Polynomial Length bits(1)

When CRCTYP (DCRCCON<15>) = 1 (CRC module is in IP Header mode):
These bits are unused.

When CRCTYP (DCRCCON<15>) = 0 (CRC module is in LFSR mode):
Denotes the length of the polynomial – 1.

bit 7 **CRCEN:** CRC Enable bit
- 1 = CRC module is enabled and channel transfers are routed through the CRC module
- 0 = CRC module is disabled and channel transfers proceed normally

Note 1: When WBO = 1, unaligned transfers are not supported and the CRCAPP bit cannot be set.

12.0 I/O PORTS

Note: This data sheet summarizes the features of the PIC32MX330/350/370/430/450/470 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 12. "I/O Ports"** (DS60001120), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

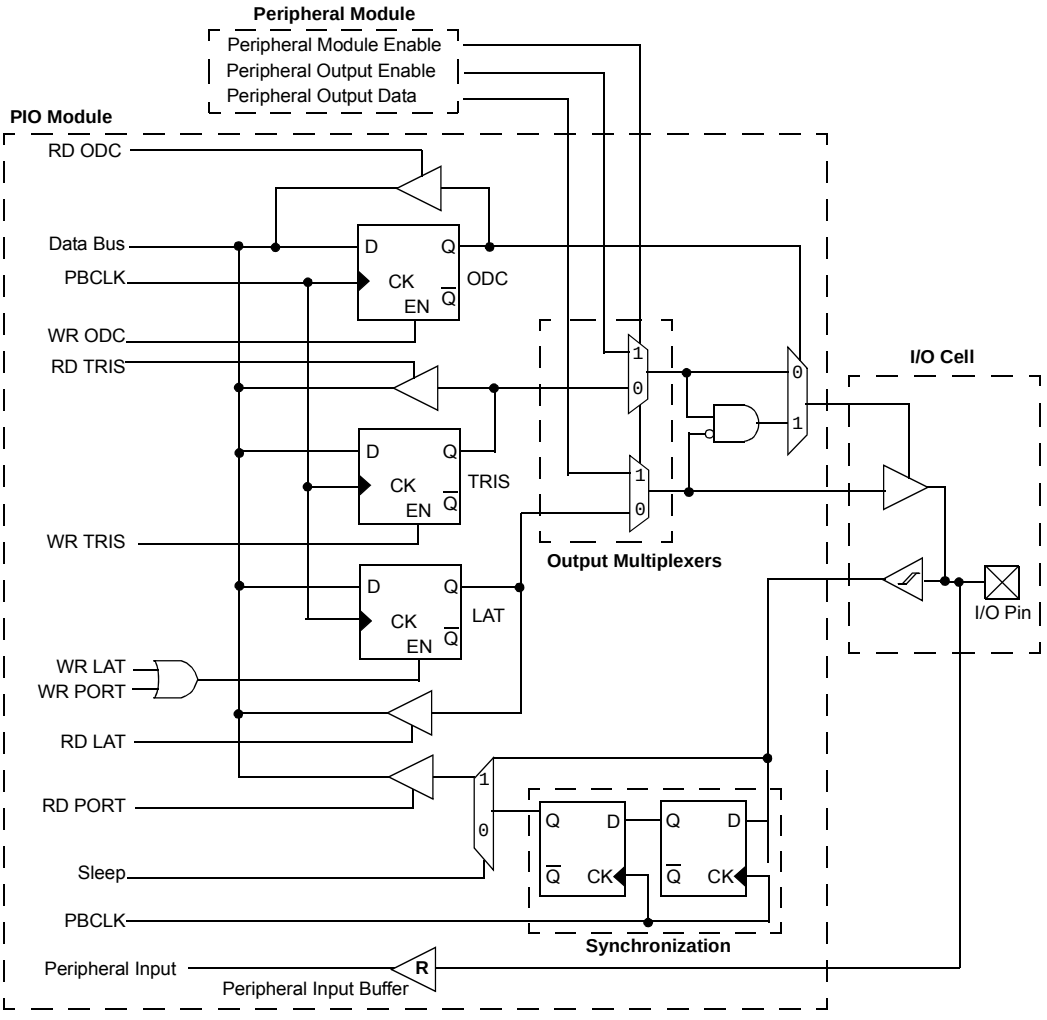
General purpose I/O pins are the simplest of peripherals. They allow the PIC® MCU to monitor and control other devices. To add flexibility and functionality, some pins are multiplexed with alternate function(s). These functions depend on which peripheral features are on the device. In general, when a peripheral is functioning, that pin may not be used as a general purpose I/O pin.

Following are key features of this module:

- Individual output pin open-drain enable/disable
- Individual input pin weak pull-up and pull-down
- Monitor selective inputs and generate interrupt when change in pin state is detected
- Operation during CPU Sleep and Idle modes
- Fast bit manipulation using CLR, SET, and INV registers

Figure 12-1 illustrates a block diagram of a typical multiplexed I/O port.

FIGURE 12-1: BLOCK DIAGRAM OF A TYPICAL MULTIPLEXED PORT STRUCTURE



Legend: R = Peripheral input buffer types may vary. Refer to Table 1-1 for peripheral details.

Note: This block diagram is a general representation of a shared port/peripheral structure for illustration purposes only. The actual structure for any specific port/peripheral combination may be different than it is shown here.

TABLE 12-1: INPUT PIN SELECTION (CONTINUED)

Peripheral Pin	[*pin name*]R SFR	[*pin name*]R bits	[*pin name*]R Value to RPn Pin Selection
INT1	INT1R	INT1R<3:0>	0000 = RPD1 0001 = RPG9 0010 = RPB14 0011 = RPD0 0100 = RPD8 0101 = RPB6 0110 = RPD5 0111 = RPB2 1000 = RPF3(4) 1001 = RPF13(3) 1010 = Reserved 1011 = RPF2(1) 1100 = RPC2(3) 1101 = RPE8(3) 1110 = Reserved 1111 = Reserved
T3CK	T3CKR	T3CKR<3:0>	
IC1	IC1R	IC1R<3:0>	
$\overline{\text{U3CTS}}$	U3CTSR	U3CTSR<3:0>	
U4RX	U4RXR	U4RXR<3:0>	
U5RX	U5RXR(3)	U5RXR<3:0>	
$\overline{\text{SS2}}$	SS2R	SS2R<3:0>	
OCFA	OCFAR	OCFAR<3:0>	

Note 1: This selection is not available on 64-pin USB devices.

2: This selection is only available on 100-pin General Purpose devices.

3: This selection is not available on 64-pin USB and General Purpose devices.

4: This selection is only available on General Purpose devices.

NOTES:

REGISTER 20-1: UxMODE: UARTx MODE REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0
	ON(1)	—	SIDL	IREN	RTSMD	—	UEN<1:0>	
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	WAKE	LPBACK	ABAUD	RXINV	BRGH	PDSEL<1:0>		STSEL

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ON:** UARTx Enable bit(1)
- 1 = UARTx is enabled. UARTx pins are controlled by UARTx as defined by UEN<1:0> and UTXEN control bits
- 0 = UARTx is disabled. All UARTx pins are controlled by corresponding bits in the PORTx, TRISx and LATx registers; UARTx power consumption is minimal

bit 14 **Unimplemented:** Read as '0'

bit 13 **SIDL:** Stop in Idle Mode bit
- 1 = Discontinue operation when device enters Idle mode
- 0 = Continue operation in Idle mode

bit 12 **IREN:** IrDA Encoder and Decoder Enable bit
- 1 = IrDA is enabled
- 0 = IrDA is disabled

bit 11 **RTSMD:** Mode Selection for $\overline{\text{UxRTS}}$ Pin bit
- 1 = $\overline{\text{UxRTS}}$ pin is in Simplex mode
- 0 = $\overline{\text{UxRTS}}$ pin is in Flow Control mode

bit 10 **Unimplemented:** Read as '0'

bit 9-8 **UEN<1:0>:** UARTx Enable bits
- 11 = UxTX, UxRX and UxBCLK pins are enabled and used; $\overline{\text{UxCTS}}$ pin is controlled by corresponding bits in the PORTx register
- 10 = UxTX, UxRX, $\overline{\text{UxCTS}}$ and $\overline{\text{UxRTS}}$ pins are enabled and used
- 01 = UxTX, UxRX and $\overline{\text{UxRTS}}$ pins are enabled and used; $\overline{\text{UxCTS}}$ pin is controlled by corresponding bits in the PORTx register
- 00 = UxTX and UxRX pins are enabled and used; $\overline{\text{UxCTS}}$ and $\overline{\text{UxRTS}}$/UxBCLK pins are controlled by corresponding bits in the PORTx register

bit 7 **WAKE:** Enable Wake-up on Start bit Detect During Sleep Mode bit
- 1 = Wake-up is enabled
- 0 = Wake-up is disabled

bit 6 **LPBACK:** UARTx Loopback Mode Select bit
- 1 = Loopback mode is enabled
- 0 = Loopback mode is disabled

Note 1: When using the 1:1 PBCLK divisor, the user software should not read/write the peripheral SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

REGISTER 21-5: PMSTAT: PARALLEL PORT STATUS REGISTER (SLAVE MODES ONLY)

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R-0	R/W-0, HS, SC	U-0	U-0	R-0	R-0	R-0	R-0
	IBF	IBOV	—	—	IB3F	IB2F	IB1F	IB0F
7:0	R-1	R/W-0, HS, SC	U-0	U-0	R-1	R-1	R-1	R-1
	OBE	OBUF	—	—	OB3E	OB2E	OB1E	OB0E

Legend:	HS = Set by Hardware	SC = Cleared by software	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **IBF:** Input Buffer Full Status bit
- 1 = All writable input buffer registers are full
- 0 = Some or all of the writable input buffer registers are empty

bit 14 **IBOV:** Input Buffer Overflow Status bit
- 1 = A write attempt to a full input byte buffer occurred (must be cleared in software)
- 0 = No overflow occurred

bit 13-12 **Unimplemented:** Read as '0'

bit 11-8 **IBxF:** Input Buffer 'x' Status Full bits
- 1 = Input Buffer contains data that has not been read (reading buffer will clear this bit)
- 0 = Input Buffer does not contain any unread data

bit 7 **OBE:** Output Buffer Empty Status bit
- 1 = All readable output buffer registers are empty
- 0 = Some or all of the readable output buffer registers are full

bit 6 **OBUF:** Output Buffer Underflow Status bit
- 1 = A read occurred from an empty output byte buffer (must be cleared in software)
- 0 = No underflow occurred

bit 5-4 **Unimplemented:** Read as '0'

bit 3-0 **OBxE:** Output Buffer 'x' Status Empty bits
- 1 = Output buffer is empty (writing data to the buffer will clear this bit)
- 0 = Output buffer contains data that has not been transmitted

22.0 REAL-TIME CLOCK AND CALENDAR (RTCC)

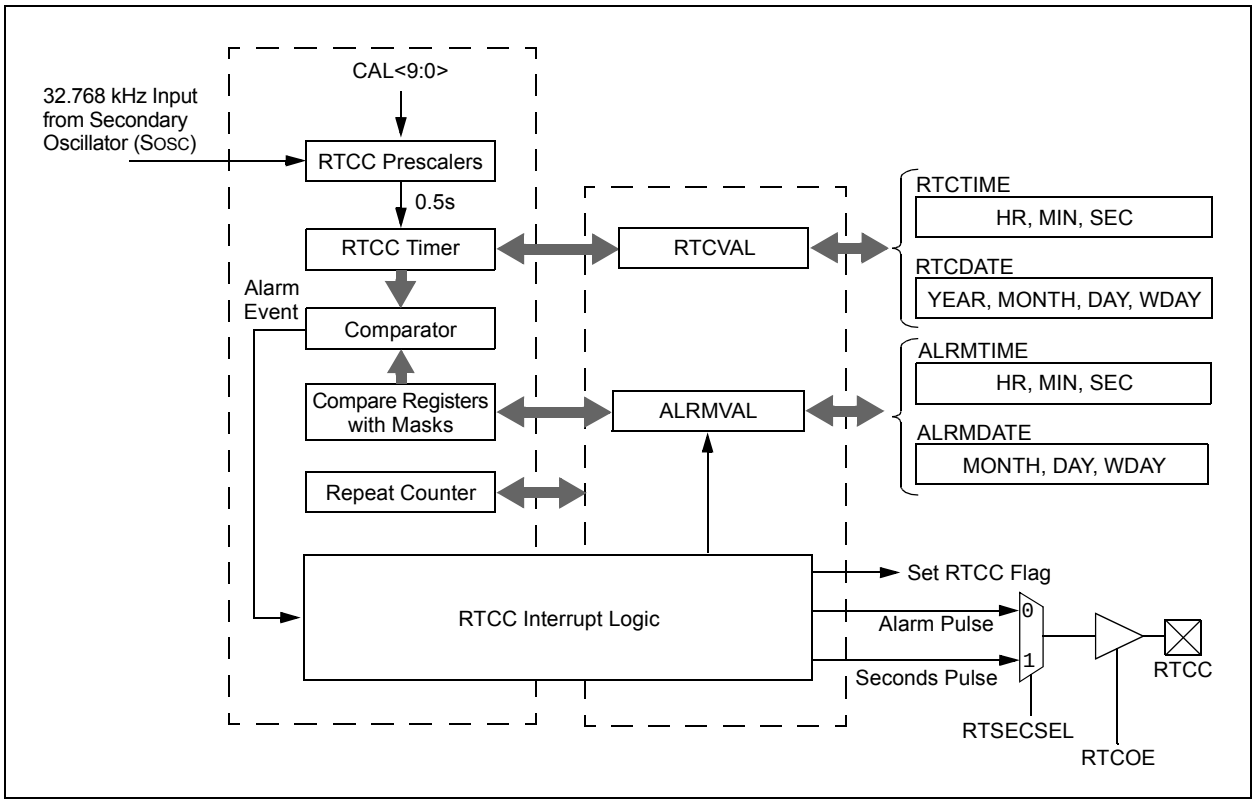
Note: This data sheet summarizes the features of the PIC32MX330/350/370/430/450/470 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 29. "Real-Time Clock and Calendar (RTCC)"** (DS60001125), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The PIC32 RTCC module is intended for applications in which accurate time must be maintained for extended periods of time with minimal or no CPU intervention. Low-power optimization provides extended battery lifetime while keeping track of time.

The following are key features of this module:

- Time: hours, minutes and seconds
- 24-hour format (military time)
- Visibility of one-half second period
- Provides calendar: Weekday, date, month and year
- Alarm intervals are configurable for half of a second, one second, 10 seconds, one minute, 10 minutes, one hour, one day, one week, one month and one year
- Alarm repeat with decrementing counter
- Alarm with indefinite repeat: Chime
- Year range: 2000 to 2099
- Leap year correction
- BCD format for smaller firmware overhead
- Optimized for long-term battery operation
- Fractional second synchronization
- User calibration of the clock crystal frequency with auto-adjust
- Calibration range: ±0.66 seconds error per month
- Calibrates up to 260 ppm of crystal error
- Requirements: External 32.768 kHz clock crystal
- Alarm pulse or seconds clock output on RTCC pin

FIGURE 22-1: RTCC BLOCK DIAGRAM



REGISTER 24-1: CMxCON: COMPARATOR CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0	R-0
	ON(1)	COE	CPOL(2)	—	—	—	—	COUT
7:0	R/W-1	R/W-1	U-0	R/W-0	U-0	U-0	R/W-1	R/W-1
	EVPOL<1:0>		—	CREF	—	—	CCH<1:0>	

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ON:** Comparator ON bit(1)
- 1 = Module is enabled. Setting this bit does not affect the other bits in this register
- 0 = Module is disabled and does not consume current. Clearing this bit does not affect the other bits in this register

bit 14 **COE:** Comparator Output Enable bit
- 1 = Comparator output is driven on the output CxOUT pin
- 0 = Comparator output is not driven on the output CxOUT pin

bit 13 **CPOL:** Comparator Output Inversion bit(2)
- 1 = Output is inverted
- 0 = Output is not inverted

bit 12-9 **Unimplemented:** Read as '0'

bit 8 **COUT:** Comparator Output bit
- 1 = Output of the Comparator is a '1'
- 0 = Output of the Comparator is a '0'

bit 7-6 **EVPOL<1:0>:** Interrupt Event Polarity Select bits
- 11 = Comparator interrupt is generated on a low-to-high or high-to-low transition of the comparator output
- 10 = Comparator interrupt is generated on a high-to-low transition of the comparator output
- 01 = Comparator interrupt is generated on a low-to-high transition of the comparator output
- 00 = Comparator interrupt generation is disabled

bit 5 **Unimplemented:** Read as '0'

bit 4 **CREF:** Comparator Positive Input Configure bit
- 1 = Comparator non-inverting input is connected to the internal CV_{REF}
- 0 = Comparator non-inverting input is connected to the CxINA pin

bit 3-2 **Unimplemented:** Read as '0'

bit 1-0 **CCH<1:0>:** Comparator Negative Input Select bits for Comparator
- 11 = Comparator inverting input is connected to the IV_{REF}
- 10 = Comparator inverting input is connected to the CxIND pin
- 01 = Comparator inverting input is connected to the CxINC pin
- 00 = Comparator inverting input is connected to the CxINB pin

Note 1: When using the 1:1 PBCLK divisor, the user's software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

2: Setting this bit will invert the signal to the comparator interrupt generator as well. This will result in an interrupt being generated on the opposite edge from the one selected by EVPOL<1:0>.

NOTES:

The processor will exit, or 'wake-up', from Sleep on one of the following events:

- On any interrupt from an enabled source that is operating in Sleep. The interrupt priority must be greater than the current CPU priority.
- On any form of device Reset
- On a WDT time-out

If the interrupt priority is lower than or equal to the current priority, the CPU will remain Halted, but the PBCLK will start running and the device will enter into Idle mode.

27.3.2 IDLE MODE

In Idle mode, the CPU is Halted but the System Clock (SYSCLK) source is still enabled. This allows peripherals to continue operation when the CPU is Halted. Peripherals can be individually configured to Halt when entering Idle by setting their respective SIDL bit. Latency, when exiting Idle mode, is very low due to the CPU oscillator source remaining active.

Note 1: Changing the PBCLK divider ratio requires recalculation of peripheral timing. For example, assume the UART is configured for 9600 baud with a PB clock ratio of 1:1 and a POSC of 8 MHz. When the PB clock divisor of 1:2 is used, the input frequency to the baud clock is cut in half; therefore, the baud rate is reduced to 1/2 its former value. Due to numeric truncation in calculations (such as the baud rate divisor), the actual baud rate may be a tiny percentage different than expected. For this reason, any timing calculation required for a peripheral should be performed with the new PB clock frequency instead of scaling the previous value based on a change in the PB divisor ratio.

2: Oscillator start-up and PLL lock delays are applied when switching to a clock source that was disabled and that uses a crystal and/or the PLL. For example, assume the clock source is switched from POSC to LPRC just prior to entering Sleep in order to save power. No oscillator start-up delay would be applied when exiting Idle. However, when switching back to POSC, the appropriate PLL and/or oscillator start-up/lock delays would be applied.

The device enters Idle mode when the SLPEN bit (OSCCON<4>) is clear and a `WAIT` instruction is executed.

The processor will wake or exit from Idle mode on the following events:

- On any interrupt event for which the interrupt source is enabled. The priority of the interrupt event must be greater than the current priority of the CPU. If the priority of the interrupt event is lower than or equal to current priority of the CPU, the CPU will remain Halted and the device will remain in Idle mode.
- On any form of device Reset
- On a WDT time-out interrupt

27.3.3 PERIPHERAL BUS SCALING METHOD

Most of the peripherals on the device are clocked using the PBCLK. The peripheral bus can be scaled relative to the SYSCLK to minimize the dynamic power consumed by the peripherals. The PBCLK divisor is controlled by PBDIV<1:0> (OSCCON<20:19>), allowing SYSCLK to PBCLK ratios of 1:1, 1:2, 1:4 and 1:8. All peripherals using PBCLK are affected when the divisor is changed. Peripherals such as the USB, Interrupt Controller, DMA, and the bus matrix are clocked directly from SYSCLK. As a result, they are not affected by PBCLK divisor changes.

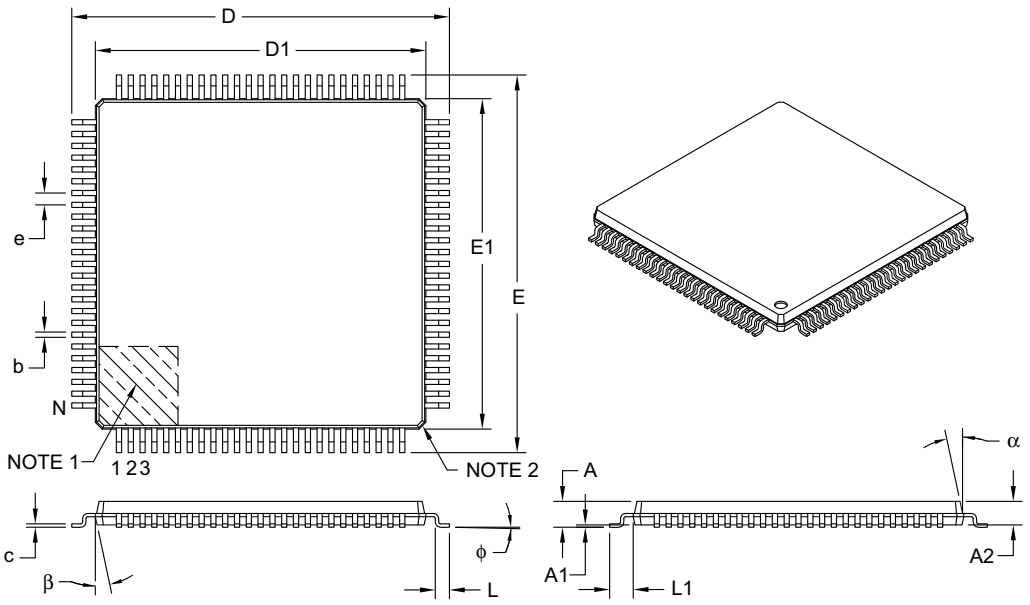
Changing the PBCLK divisor affects:

- The CPU to peripheral access latency. The CPU has to wait for next PBCLK edge for a read to complete. In 1:8 mode, this results in a latency of one to seven SYSCLKs.
- The power consumption of the peripherals. Power consumption is directly proportional to the frequency at which the peripherals are clocked. The greater the divisor, the lower the power consumed by the peripherals.

To minimize dynamic power, the PB divisor should be chosen to run the peripherals at the lowest frequency that provides acceptable system performance. When selecting a PBCLK divider, peripheral clock requirements, such as baud rate accuracy, should be taken into account. For example, the UART peripheral may not be able to achieve all baud rate values at some PBCLK divider depending on the SYSCLK value.

100-Lead Plastic Thin Quad Flatpack (PF) – 14x14x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		100	
Lead Pitch	e		0.50 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E		16.00 BSC	
Overall Length	D		16.00 BSC	
Molded Package Width	E1		14.00 BSC	
Molded Package Length	D1		14.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

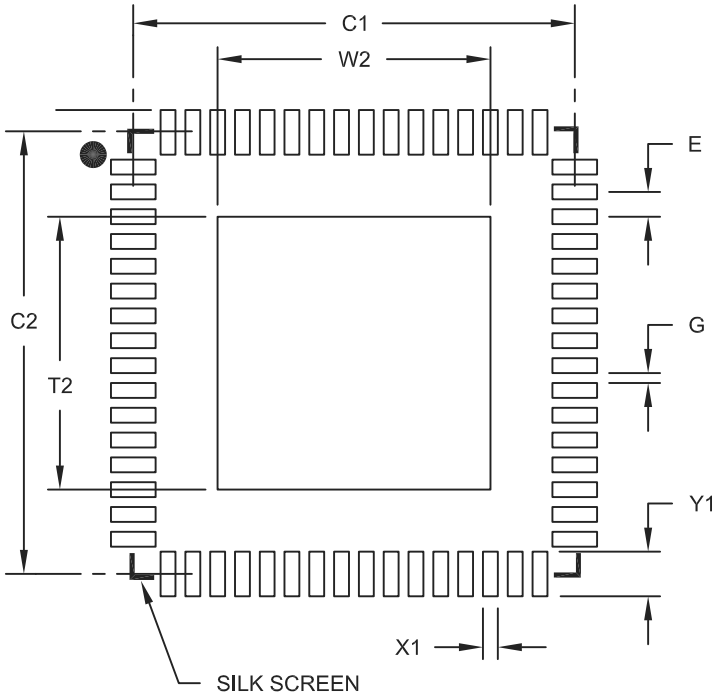
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-110B

64-Lead Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body [QFN]
With 0.40 mm Contact Length and 5.40x5.40mm Exposed Pad

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Optional Center Pad Width	W2			5.50
Optional Center Pad Length	T2			5.50
Contact Pad Spacing	C1		8.90	
Contact Pad Spacing	C2		8.90	
Contact Pad Width (X64)	X1			0.30
Contact Pad Length (X64)	Y1			0.85
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2154A

NOTES:

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